

ABSTRACT OF THE DISCLOSURE

In a circuit board having lands 2 each of which has a through hole 4 through which a lead of an electrical part is inserted, the lead 3 and the land 2 being mounted in the circuit board by using lead-free solder 6, the width of the land 2 corresponding to the difference in radius between the land 2 and the through hole 4 is set to about 0.40mm or more. The width of the land 2 is set to such a value that the land exfoliation due to the solidification/shrinkage of the lead-free solder 6 and the shrinkage of the circuit board in the thickness direction can be prevented. The circuit board 1 has circuit wires at least on both the surface and the back surface.

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